

ABSTRACT

A high-power semiconductor module (10) has a number of flat semiconductor chips (14) which rest with their lower face flat on a base plate (11), establishing first electrical contacts, and have a cover plate (13), which is arranged parallel to the base plate (11), applied to their upper face with pressure, establishing second electrical contacts.

In a module such as this, simplified cooling is made possible in that those faces, or outer faces, of the base plate (11) and of the cover plate (13) which face away from the semiconductor chips (14) are each electrically isolated from the semiconductor chips (14).

(Figure 3)

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List of reference symbols

10	High-power semiconductor module
11	Base plate
12	Housing (electrically insulating)
13	Cover plate
14	Semiconductor chip
15, 16	Contact spring
17	Substrate (electrically insulating)
18, 19	Metal coating
20, 22	Isolation plate
21	Contact plate (emitter)
23	Contact plate (collector)
24	Cooling apparatus

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